

N-Channel Power MOSFET

60V, 23A, 12mΩ

FEATURES

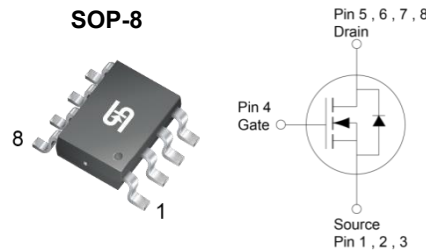
- Low $R_{DS(on)}$ to minimize conductive losses
- Logic level
- Low gate charge for fast power switching
- 100% UIS and R_g tested
- Compliant to RoHS directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

KEY PERFORMANCE PARAMETERS

PARAMETER	VALUE	UNIT
V_{DS}	60	V
$R_{DS(on)}$ (max)	$V_{GS} = 10V$	12
	$V_{GS} = 4.5V$	15
Q_g	19	nC

APPLICATIONS

- Motor Control for BLDC
- Battery Power Management



Note: MSL 1 (Moisture Sensitivity Level) per J-STD-020

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	I_D	$T_C = 25^\circ\text{C}$	23
		$T_A = 25^\circ\text{C}$	10
Pulsed Drain Current (Note 1)	I_{DM}	92	A
Single Pulse Avalanche Current (Note 2)	I_{AS}	19	A
Single Pulse Avalanche Energy (Note 2)	E_{AS}	54	mJ
Total Power Dissipation	P_D	$T_C = 25^\circ\text{C}$	12.5
		$T_C = 125^\circ\text{C}$	2.5
Total Power Dissipation	P_D	$T_A = 25^\circ\text{C}$	2.2
		$T_A = 125^\circ\text{C}$	0.4
Operating Junction and Storage Temperature Range	T_J, T_{STG}	- 55 to +150	$^\circ\text{C}$

THERMAL PERFORMANCE

PARAMETER	SYMBOL	LIMIT	UNIT
Junction to Case Thermal Resistance	$R_{\theta JC}$	10	$^\circ\text{C/W}$
Junction to Ambient Thermal Resistance	$R_{\theta JA}$	57	$^\circ\text{C/W}$

Thermal Performance Notes: $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistances. The case-thermal reference is defined at the solder mounting surface of the drain pins. $R_{\theta JA}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.

ELECTRICAL SPECIFICATIONS ($T_A = 25^\circ\text{C}$ unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	MIN	TYP	MAX	UNIT
Static (Note 3)						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	BV_{DSS}	60	--	--	V
Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250\mu A$	$V_{GS(TH)}$	1.2	1.7	2.5	V
Gate-Source Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$	I_{GSS}	--	--	± 100	nA
Drain-Source Leakage Current	$V_{GS} = 0V, V_{DS} = 60V$	I_{DSS}	--	--	1	μA
	$V_{GS} = 0V, V_{DS} = 60V$ $T_J = 125^\circ\text{C}$		--	--	100	
Drain-Source On-State Resistance	$V_{GS} = 10V, I_D = 10A$	$R_{DS(on)}$	--	10.4	12	m Ω
	$V_{GS} = 4.5V, I_D = 10A$		--	11.9	15	
Forward Transconductance	$V_{DS} = 5V, I_D = 10A$	g_{fs}	--	38	--	S
Dynamic (Note 4)						
Total Gate Charge	$V_{GS} = 10V, V_{DS} = 30V,$ $I_D = 10A$	Q_g	--	37	--	nC
Total Gate Charge	$V_{GS} = 4.5V, V_{DS} = 30V,$ $I_D = 10A$	Q_g	--	19	--	
Gate-Source Charge		Q_{gs}	--	6	--	
Gate-Drain Charge		Q_{gd}	--	8	--	
Input Capacitance	$V_{GS} = 0V, V_{DS} = 30V$ $f = 1.0\text{MHz}$	C_{iss}	--	2193	--	pF
Output Capacitance		C_{oss}	--	208	--	
Reverse Transfer Capacitance		C_{rss}	--	88	--	
Gate Resistance	$f = 1.0\text{MHz}$	R_g	0.4	1.5	3	Ω
Switching (Note 4)						
Turn-On Delay Time	$V_{GS} = 10V, V_{DS} = 30V,$ $I_D = 11A, R_G = 2\Omega,$	$t_{d(on)}$	--	6.4	--	ns
Turn-On Rise Time		t_r	--	3.6	--	
Turn-Off Delay Time		$t_{d(off)}$	--	23	--	
Turn-Off Fall Time		t_f	--	5	--	
Source-Drain Diode (Note 3)						
Forward Voltage	$V_{GS} = 0V, I_S = 10A$	V_{SD}	--	--	1	V
Reverse Recovery Time	$I_S = 10A,$ $dI/dt = 100A/\mu s$	t_{rr}	--	17	--	ns
Reverse Recovery Charge		Q_{rr}	--	13	--	nC

Notes:

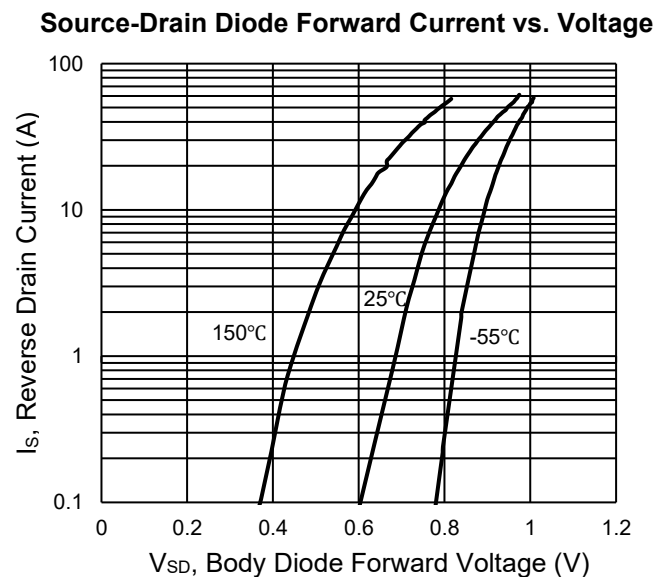
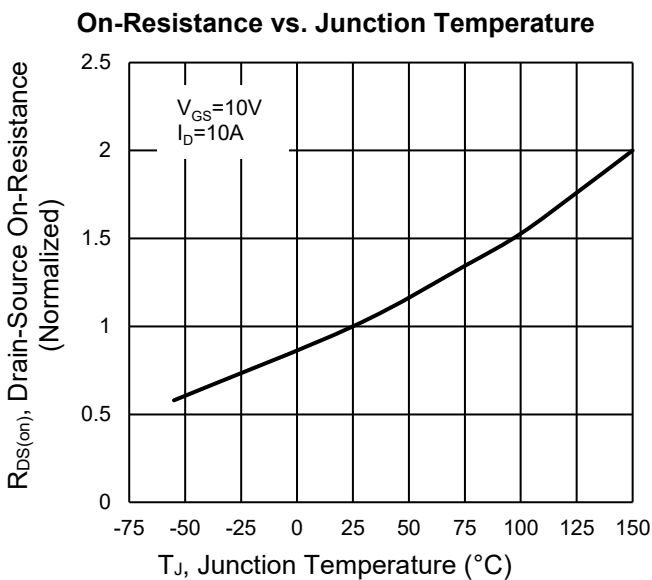
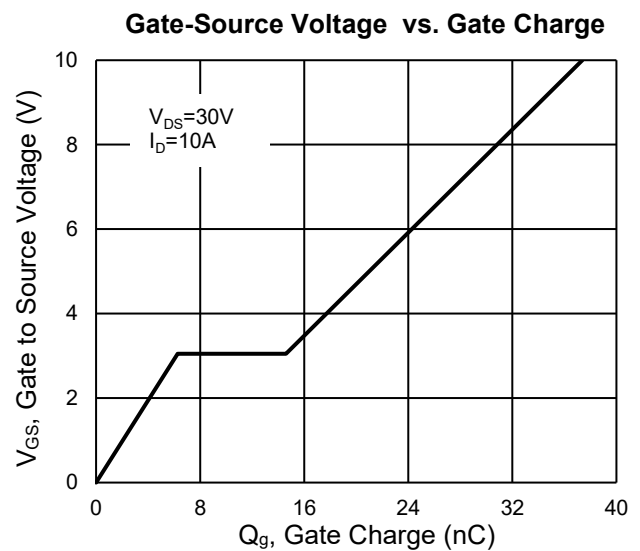
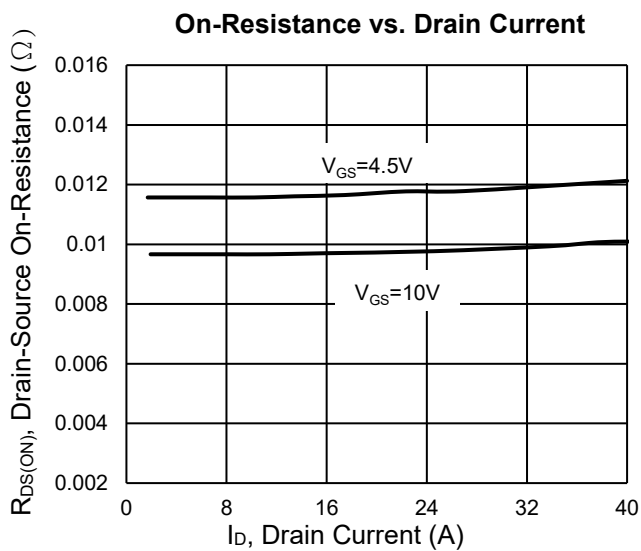
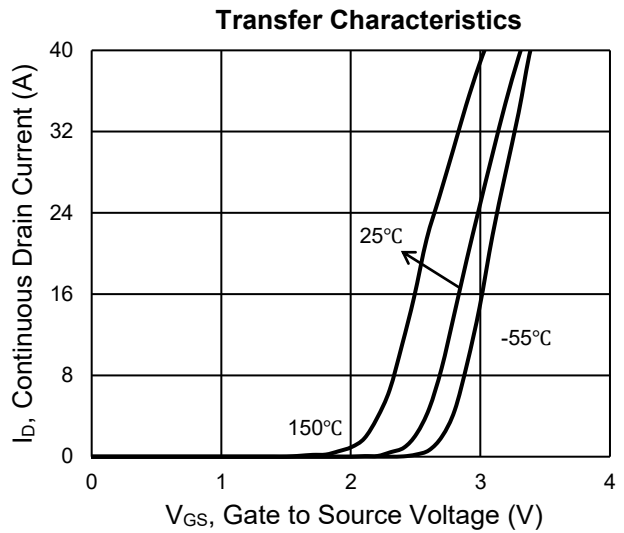
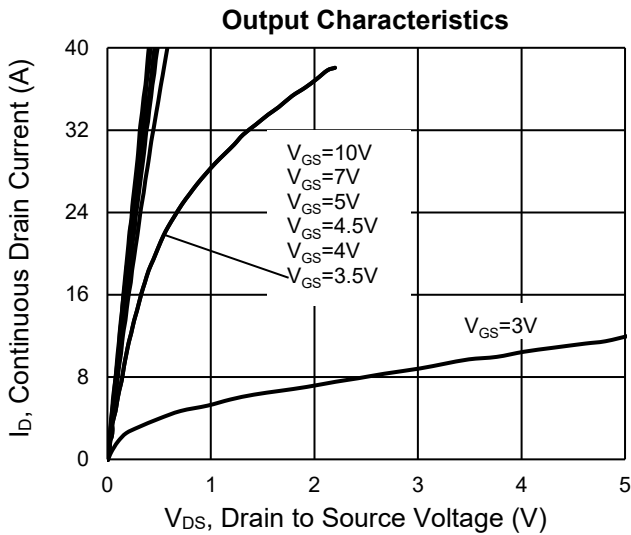
1. Current limited by package.
2. $L = 0.3\text{mH}, V_{GS} = 10V, V_{DD} = 30V, R_G = 25\Omega, I_{AS} = 19A,$ Starting $T_J = 25^\circ\text{C}$
3. Pulse test: Pulse Width $\leq 300\mu s,$ duty cycle $\leq 2\%$.
4. Switching time is essentially independent of operating temperature.

ORDERING INFORMATION

ORDERING CODE	PACKAGE	PACKING
TSM120N06LCS RLG	SOP-8	2,500pcs / 13" Reel

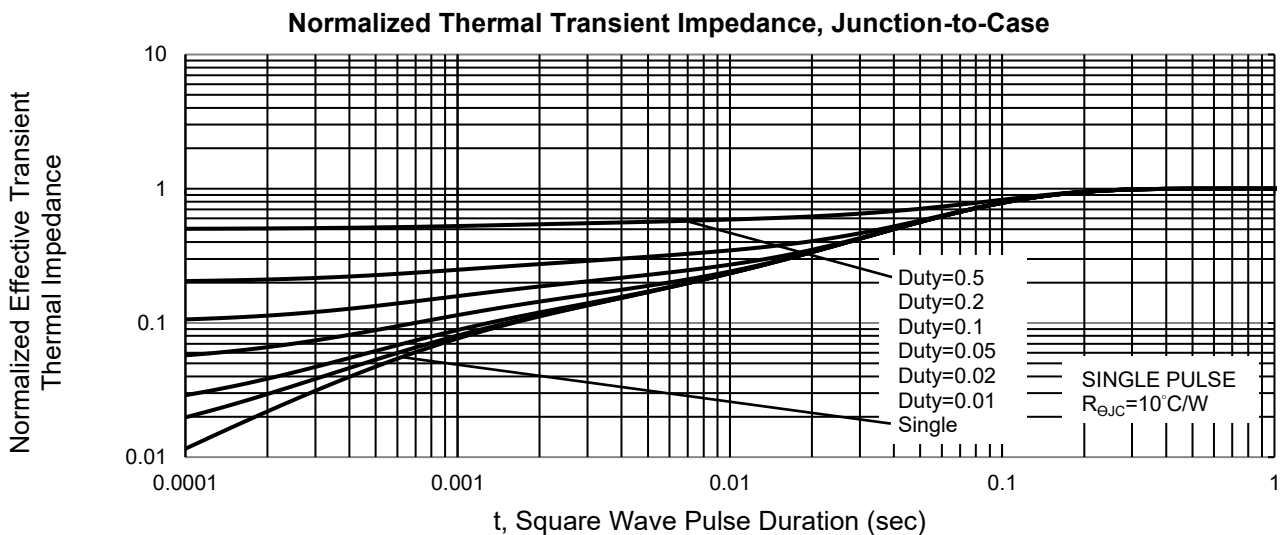
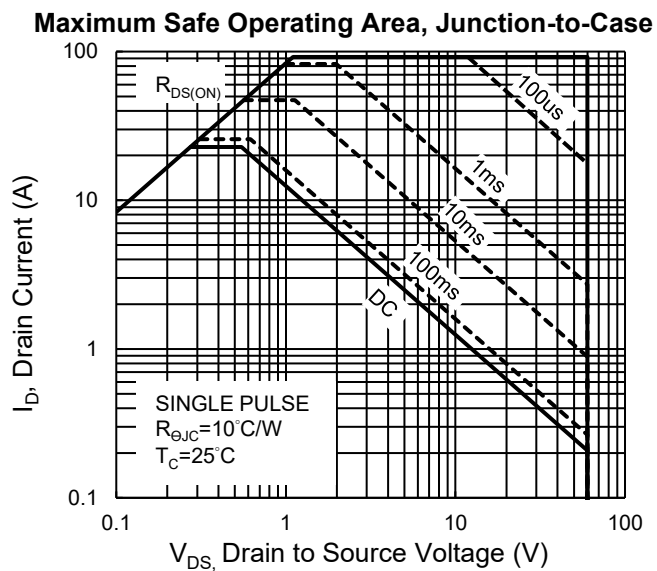
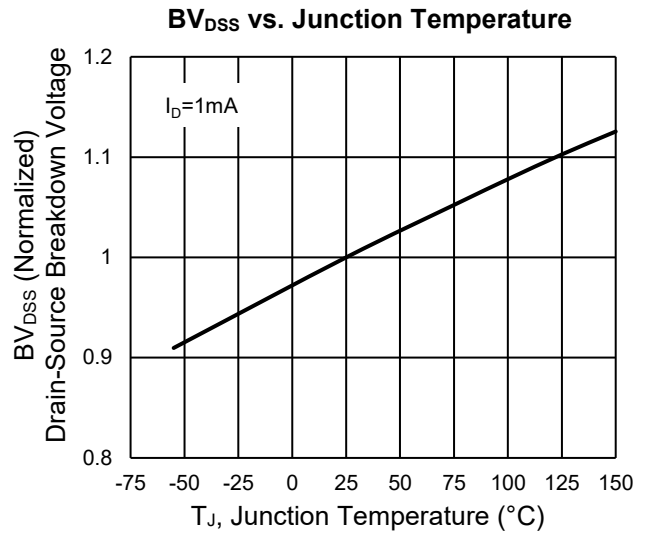
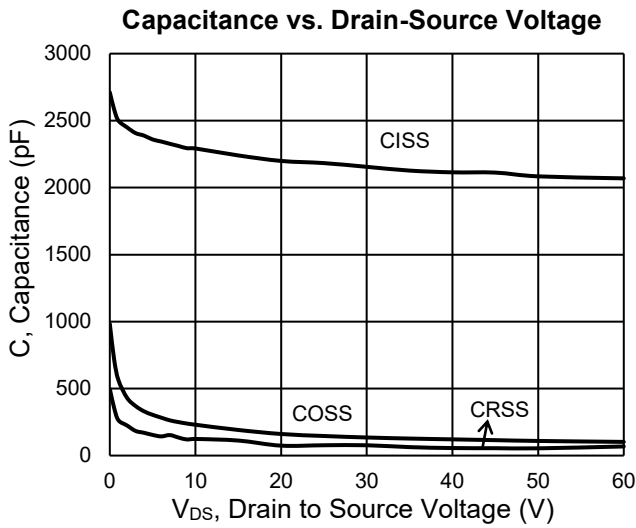
CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)



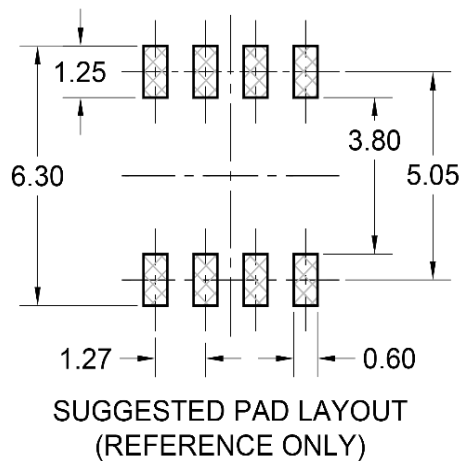
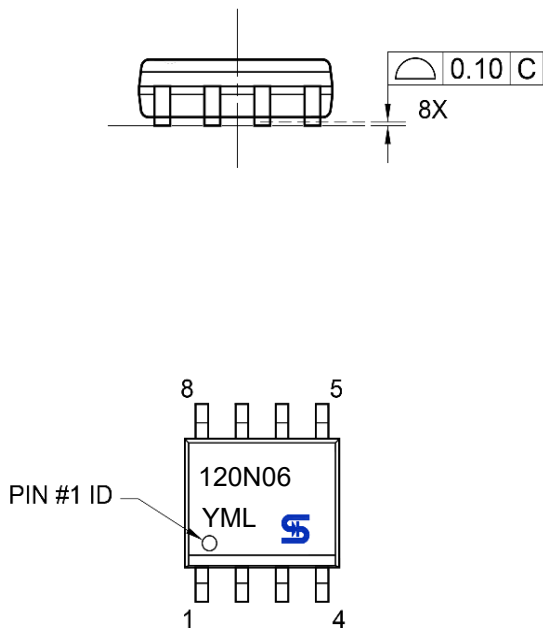
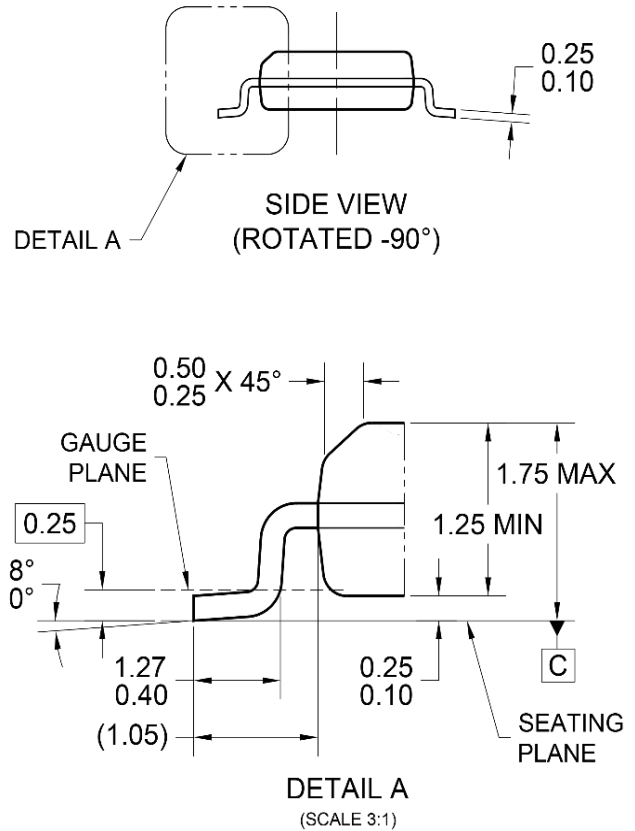
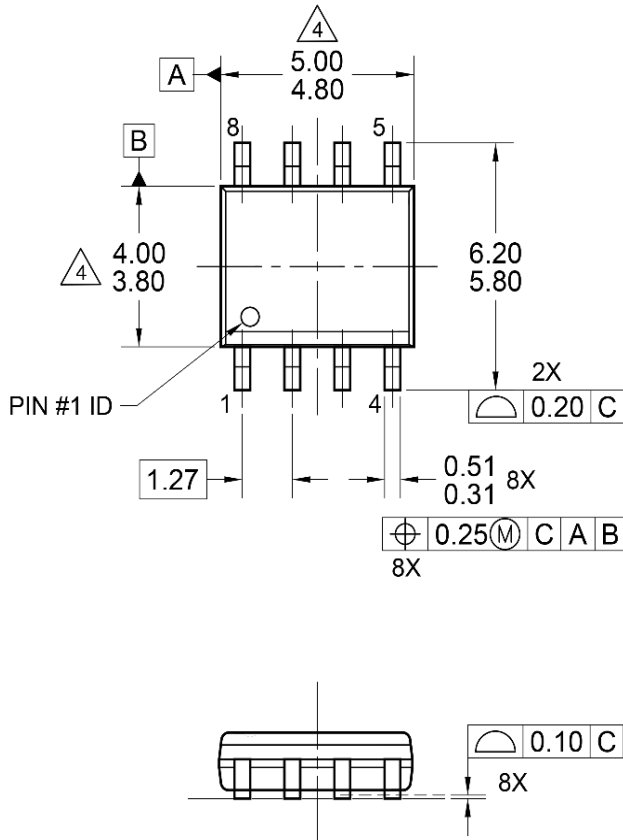
CHARACTERISTICS CURVES

($T_A = 25^\circ\text{C}$ unless otherwise noted)



PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

SOP-8



MARKING DIAGRAM

- 120N06 = Device Code
- Y = Year Code
- M = Month Code for Halogen Free Product
(O=Jan, P=Feb, Q=Mar, R=Apr, S=May, T=Jun, U=Jul, V=Aug, W=Sep, X=Oct, Y=Nov, Z=Dec)
- L = Lot Code

NOTES: UNLESS OTHERWISE SPECIFIED

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PACKAGE OUTLINE REFERENCE: JEDEC MS-012, ISSUE G, VARIATION AA.
4. MOLDED PLASTIC BODY DIMENSIONS DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
5. DWG NO REF: HQ2SD07-SOP8STD-028 REV A.

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